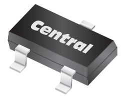
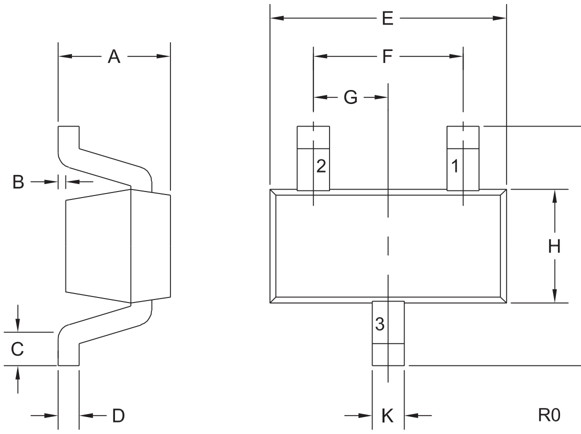
Package Details

SOT-523W Case



Central Semiconductor Corp.

Mechanical Drawing



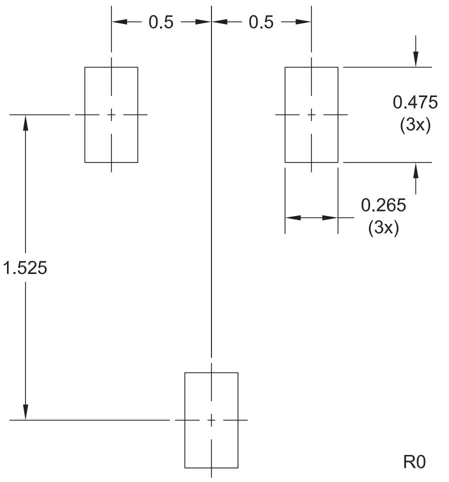
DIMENSIONS				
	INCHES		MILLIMETERS	
SYMBOL	MIN	MAX	MIN	MAX
A	-	0.031	-	0.80
B	0.000	0.004	0.00	0.10
C	0.006	0.012	0.15	0.30
D	0.005	0.006	0.13	0.15
E	0.058	0.066	1.48	1.68
F	0.039		1.00	
G	0.020		0.50	
H	0.026	0.034	0.66	0.86
J	0.059	0.067	1.50	1.70
K	0.007	0.009	0.19	0.24

SOT-523W (REV: R0)

Lead Code:
Reference individual
device datasheet.

Part Marking: 2-3 Character Alpha/Numeric Code

Mounting Pad Geometry (Dimensions in mm)

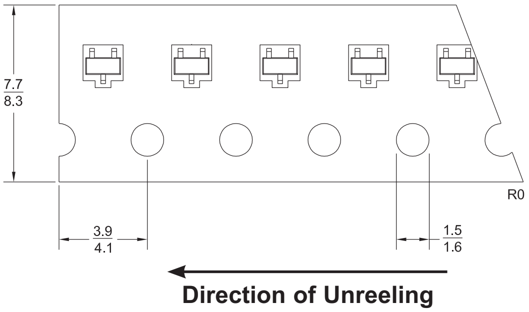


Package Details

SOT-523W Case

Tape Dimensions and Orientation (Dimensions in mm)

Tape Width: 8mm



Devices are taped in
accordance with
Electronic Industries
Association Standard
EIA-481-1-A

Packaging Base

7” Reel = 3,000 pcs.

Reel Labeling Information

Each reel is labeled with the following information:
Central Part Number, Customer Part Number, Purchase Order Number,
Quantity, Lot Number, Date Code, Ship Date and Marking Code.

Reel Packing Information

Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
7”	9	27,000	9x9x5	23x23x13	3	2
	18	54,000	9x9x9	23x23x23	6	3
	40	120,000	21x9x9	53x23x23	13	6
	108	324,000	27x9x17	69x23x43	34	16

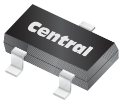
Ordering Information

- For devices taped and reeled on 7” reels, add TR suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

R0 (31-October 2011)

Material Composition Specification

SOT-523W Case



Device average mass . . . . **2.3 mg**

Fluctuation margin . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	3.02%	0.07	Si	7440-21-3	3.02%	0.07	30,172
bond wire	gold	0.56%	0.013	Au	7440-57-5	0.56%	0.013	5,603
leadframe	alloy 42 w/ copper & silver plating	31.55%	0.732	Fe	7439-89-6	16.16%	0.375	161,638
				Ni	7440-02-0	12.50%	0.29	125,000
				Cu	7440-50-8	2.59%	0.06	25,862
				Ag	7440-22-4	0.30%	0.007	3,017
encapsulation*	EMC GREEN	60.34%	1.4	silica (fused)	60676-86-0	40.22%	0.933	402,155
				epoxy resin	29690-82-2	6.94%	0.161	69,397
				phenol resin	9003-35-4	6.94%	0.161	69,397
				carbon black	1333-86-4	0.22%	0.005	2,155
				metal hydroxide	1309-42-8	6.03%	0.14	60,345
plating	100% matte tin	4.53%	0.105	Sn	7440-31-5	4.53%	0.105	45,259

*EMC GREEN molding compound is Halogen-Free.

R0 (7-November 2011)